

Features

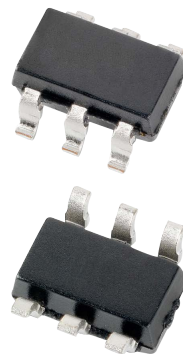
- Ultra low capacitance: 0.3pF typical (I/O to I/O)
- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Up to four data lines and one power line protects
- JEDEC SOT23-6 package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: $\pm 20\text{kV}$
Contact discharge: $\pm 15\text{kV}$
 - IEC61000-4-5 (Lightning) 4.5A (8/20 μs)
- RoHS Compliant

Mechanical Characteristics

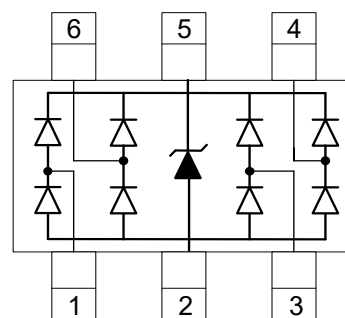
- Package: SOT23-6
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- Terminal Connections: See Diagram Below
- Marking Information: See Below

Applications

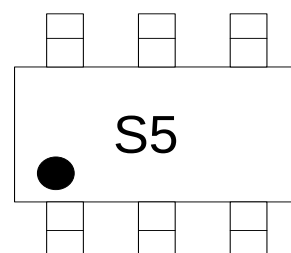
- USB 2.0 Power and Data lines protection
- Digital Visual Interface (DVI)
- Monitors and Flat Panel Displays
- Video Graphic Cards
- Notebook and PC Computers



SOT-23-6



Circuit diagram



S5 = Device Marking Code

Dot denotes Pin1

Marking (Top View)

Ordering Information

Part Number	Packaging	Reel Size
SRV05-4-P-T7	3000/Tape & Reel	7 inch

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

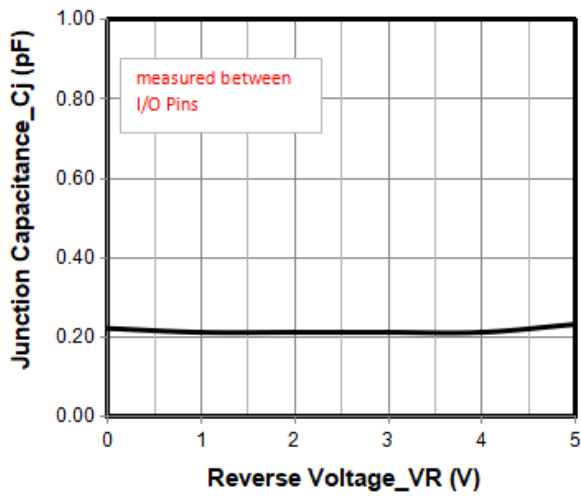
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	Ppk	60	W
Peak Pulse Current (8/20 μs)	I _{PP}	4.5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	± 20 ± 15	kV
Operating Temperature Range	T _J	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	T _{stg}	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

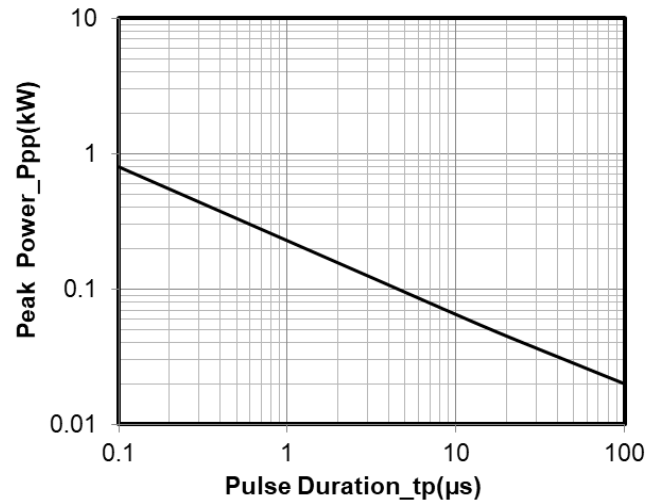
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V _{RWM}			5	V	Any I/O pin to ground
Breakdown Voltage	V _{BR}	6			V	I _T = 1mA, any I/O pin to ground
Reverse Leakage Current	I _R			0.5	μA	V _{RWM} = 5V, any I/O pin to ground
Forward Voltage	V _F		1.0	1.2	V	I _F = 15mA, ground to pin 1,3,4,5,6
Clamping Voltage	V _C		9	12	V	I _{PP} = 1A (8 x 20 μs pulse), any I/O pin to ground
Clamping Voltage	V _C		12	15	V	I _{PP} = 4.5A (8 x 20 μs pulse), any I/O pin to ground
Junction Capacitance	C _J		15	18	pF	I _{PP} = 17A (8 x 20 μs pulse), any V _{cc} pin 5 to ground
Clamping Voltage	V _C		0.3	0.4	pF	V _R = 0V, f = 1MHz, any I/O pin to I/O pin
Junction Capacitance	C _J		0.6	0.8	pF	V _R = 0V, f = 1MHz, any I/O pin to ground

Note 1: I/O pins are Pin 1, 3, 4 and 6.

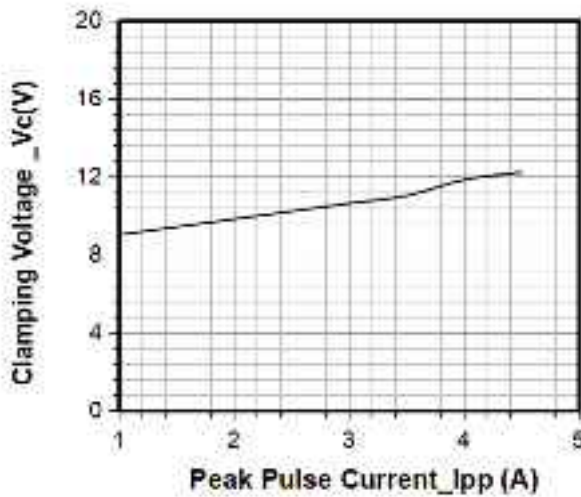
Typical Performance Characteristics (TA=25°C unless otherwise Specified)



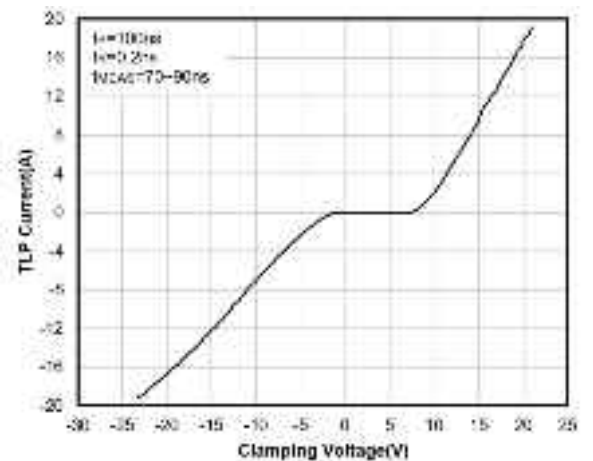
Junction Capacitance vs. Reverse Voltage



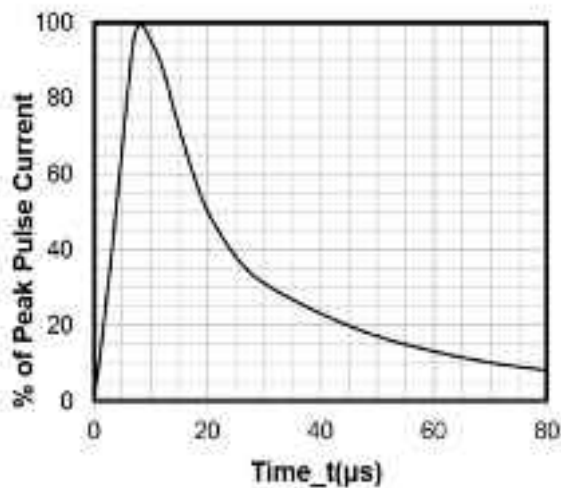
Peak Pulse Power vs. Pulse Time



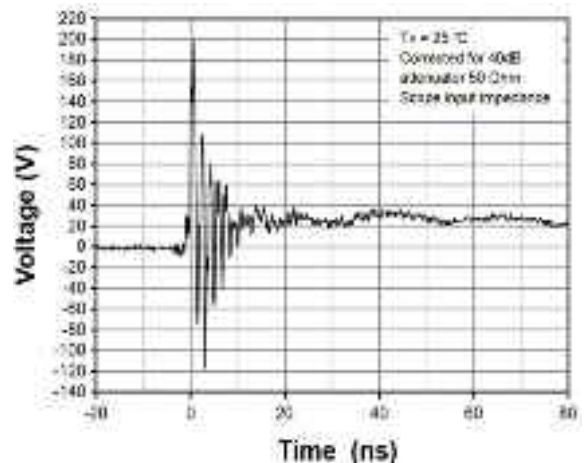
Clamping Voltage vs. Peak Pulse Current



TLP Curve



8 X 20μs Pulse Waveform

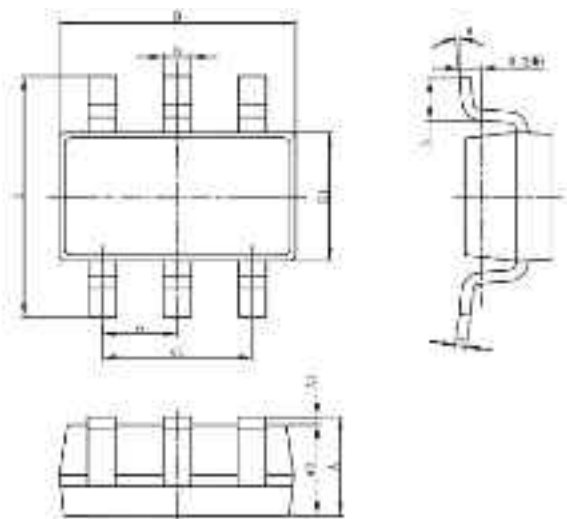


Note: Data is taken with a 10x attenuator

ESD Clamping Voltage

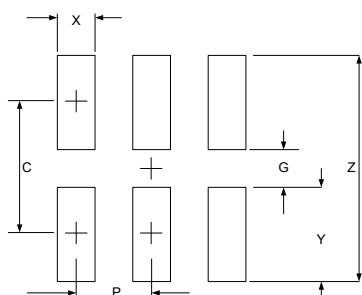
8 kV Contact per IEC61000-4-2

SOT23-6 Package Outline Drawing



SYM	DIMENSIONS			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.090	1.450	0.0035	0.057
A1	0.000	0.150	0.000	0.006
A2	0.090	1.300	0.035	0.051
b	0.250	0.500	0.010	0.020
c	0.100	0.200	0.004	0.008
D	2.800	3.100	0.110	0.122
E1	1.500	1.750	0.060	0.069
E	2.650	3.000	0.104	0.120
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
C	2.50	0.098
G	1.40	0.055
P	0.95	0.037
X	0.60	0.024
Y	1.10	0.043
Z	3.60	0.141